

Title (en)

LAMINATE COMPRISING AN INTEGRATED ELECTRONIC COMPONENT

Title (de)

LAMINAT MIT INTEGRIERTEM ELEKTRONISCHEN BAUTEIL

Title (fr)

LAMINÉ DOTÉ D'UN COMPOSANT ÉLECTRONIQUE INTÉGRÉ

Publication

**EP 2636061 A1 20130911 (DE)**

Application

**EP 11785581 A 20111024**

Priority

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Abstract (en)

[origin: WO2012059187A1] The invention relates to methods for producing a laminate that is for contacting at least one electronic component. In said method, an insulating layer is arranged between a first metal layer and a second metal layer, the metal layers are contacted with each other, at least one cavity is produced in the insulating layer, the metal layers are laminated with the insulating layer, a recess is produced in the first metal layer for receiving the electronic component, and the electronic component is inserted therein. The invention also relates to a laminate produced by such a method, and to the use thereof as a circuit board, sensor, LED lamp, mobile phone component, control system, controller or mobile phone flash LED.

IPC 8 full level

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CPC (source: EP KR US)

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Citation (search report)

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